

P54/74FCT240/A/C (P54/74PCT240/A/C) P54/74FCT241/A/C (P54/74PCT241/A/C) P54/74FCT244/A/C (P54/74PCT244/A/C) OCTAL BUFFERS/LINE DRIVERS W/ 3-STATE OUTPUTS

FEATURES

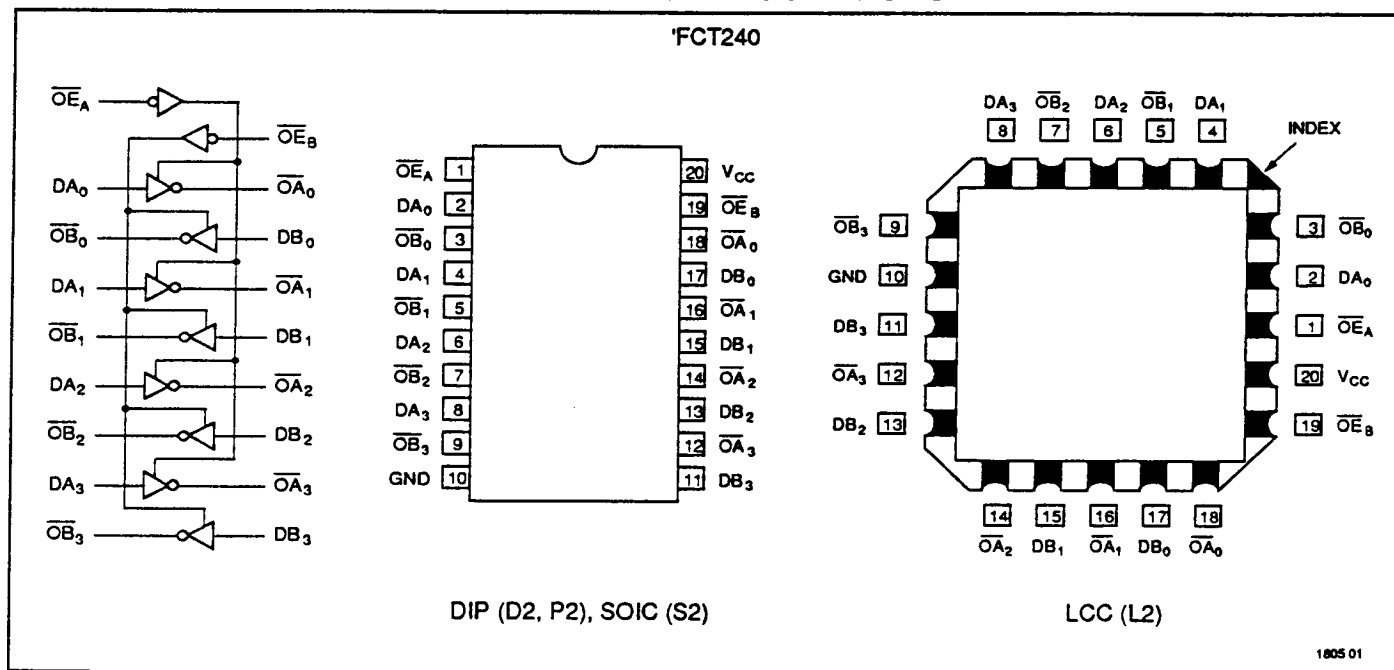
- Function, Pinout, and Drive Compatible with the FCT and F Logic
- FCT-C speed at 4.1ns max. (Com'I)
FCT-A speed at 4.8ns max. (Com'I)
- CMOS V_{OH} Levels for Low Power Consumption
— Typically 1/3 of FAST Bipolar Logic
- Edge-rate Control Circuitry for Significantly Improved Noise Characteristics
- ESD protection exceeds 2000V
- Inputs and Outputs Interface Directly with TTL, NMOS, and CMOS Devices
- Outputs Meet Levels Required for CMOS Static RAM Low Power Standby Mode
- 64 mA Sink Current (Com'I), 48 mA (Mil)
15 mA Source Current (Com'I), 12 mA (Mil)
- Manufactured In 0.8 micron PACE Technology™

DESCRIPTION

The 'FCT240, 'FCT241 and 'FCT244 are octal buffers and line drivers designed to be employed as memory address drivers, clock drivers and bus-oriented transmitters/receivers. The devices provide speed and drive capabilities

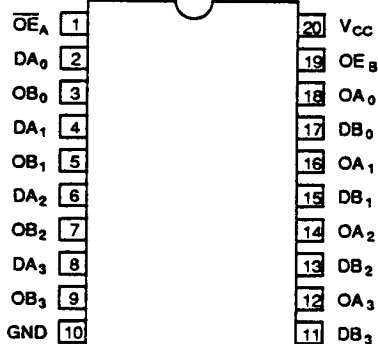
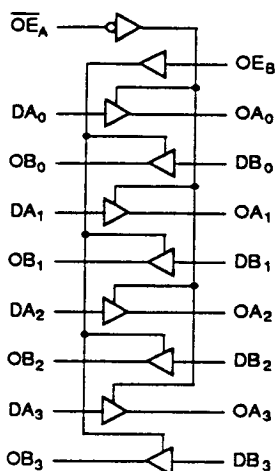
equivalent to their fastest bipolar logic counterparts while reducing power dissipation. The input and output voltage levels allow direct interface with TTL, NMOS and CMOS devices without external components.

FUNCTIONAL BLOCK DIAGRAM and PIN CONFIGURATIONS

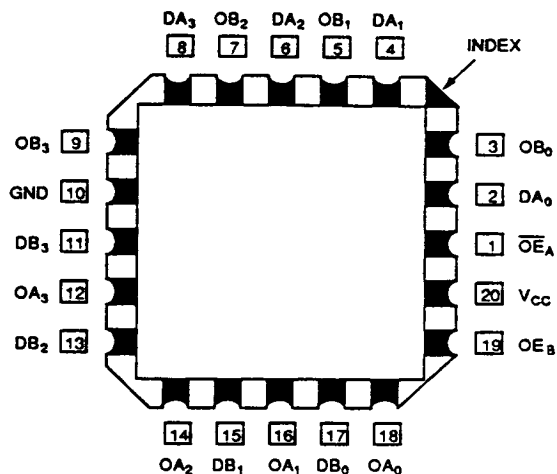


FUNCTIONAL BLOCK DIAGRAM and PIN CONFIGURATIONS

'FCT241



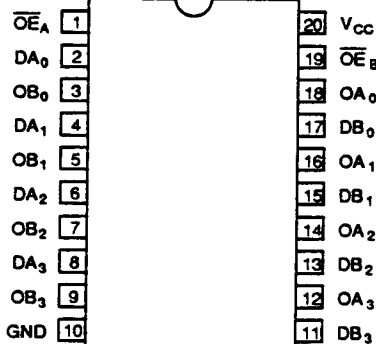
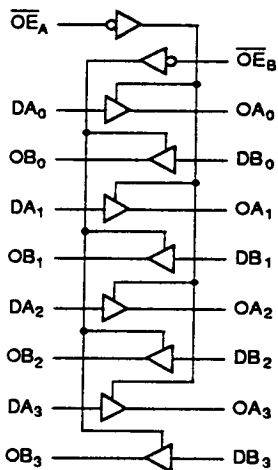
DIP (D2, P2), SOIC (S2)



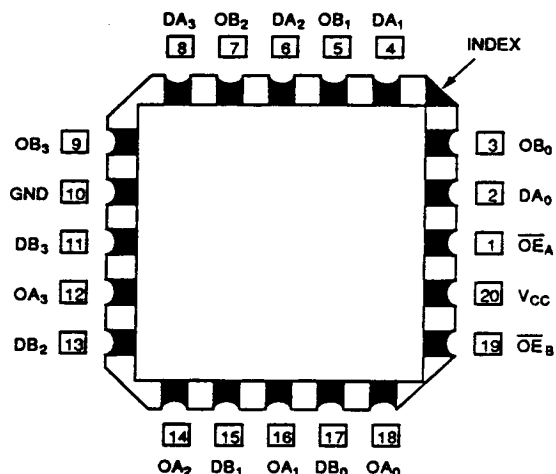
LCC (L2)

1805 02

'FCT244



DIP (D2, P2), SOIC (S2)



LCC (L2)

1805 03

ABSOLUTE MAXIMUM RATINGS^{1,2}

Symbol	Parameter	Value	Unit
T _{STG}	Storage Temperature	−65 to +150	°C
T _A	Ambient Temperature Under Bias	−65 to +135	°C
V _{CC}	V _{CC} Potential to Ground	−0.5 to +7.0	V
I _{IN}	Input Current	−30 to +5.0	mA

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Notes:

1. Operation beyond the limits set forth in the above table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.

Symbol	Parameter	Value	Unit
I _{OUTPUT}	Current Applied to Output	120	mA
V _{IN}	Input Voltage	−0.5 to V _{CC} + 0.5	V
V _{OUT}	Voltage Applied to Output	−0.5 to V _{CC} + 0.5	V

1805 Tbl 02

2. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.

RECOMMENDED OPERATING CONDITIONS

Free Air Ambient Temperature	Min	Max
Military	−55°C	+125°C
Commercial	0°C	+70°C

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Supply Voltage (V _{CC})	Min	Max
Military	+4.5V	+5.5V
Commercial	+4.75V	+5.25V

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DC ELECTRICAL CHARACTERISTICS (Over recommended operating conditions)

Symbol	Parameter	Min	Typ ¹	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		
V _{IL}	Input LOW Voltage			0.8	V		
V _H	Hysteresis		0.35		V		All inputs
V _{IK}	Input Clamp Diode Voltage		−0.7	−1.2	V	MIN	I _{IN} = −18mA
V _{OH}	Output HIGH Voltage	V _{CC} = 3V, V _{IN} = 0.2V, or V _{CC} − 0.2V		V _{CC} − 0.2		V	I _{OH} = −32μA
		Military/Commercial (CMOS)		V _{CC} − 0.2	V _{CC}	MIN	I _{OH} = −300μA
		Military (TTL)		2.4	4.3	MIN	I _{OH} = −12mA
		Commercial (TTL)		2.7	4.3	MIN	I _{OH} = −15mA
V _{OL}	Output LOW Voltage	V _{CC} = 3V, V _{IN} = 0.2V, or V _{CC} − 0.2V		GND	0.2	V	I _{OL} = 300μA
		Military/Commercial (CMOS)		GND	0.2	V	I _{OL} = 300μA
		Military (TTL)		0.3	0.55	V	I _{OL} = 48mA
		Commercial (TTL)		0.3	0.55	V	I _{OL} = 64mA
I _{IH}	Input HIGH Current			5	μA	MAX	V _{IN} = V _{CC}
I _{IL}	Input LOW Current			−5	μA	MAX	V _{IN} = GND
I _{IH}	Input HIGH Current ³			5	μA	MAX	V _{IN} = 2.7V
I _{IL}	Input LOW Current ³			−5	μA	MAX	V _{IN} = 0.5V
I _{OZH}	Off State I _{OUT} HIGH-Level Output Current			10	μA	MAX	V _{OUT} = V _{CC}
I _{OZL}	Off State I _{OUT} LOW-Level Output Current			−10	μA	MAX	V _{OUT} = GND
I _{OZH}	Off State I _{OUT} HIGH-Level Output Current ³			10	μA	MAX	V _{OUT} = 2.7V
I _{OZL}	Off State I _{OUT} LOW-Level Output Current ³			−10	μA	MAX	V _{OUT} = 0.5V
I _{OS}	Output Short Circuit Current ²	−60	−120		mA	MAX	V _{OUT} = 0.0V
C _{IN}	Input Capacitance ³		5	10	pF		All inputs
C _{OUT}	Output Capacitance ³		9	12	pF		All outputs

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Notes:

- Typical limits are at V_{CC} = 5.0V, T_A = +25°C ambient.
- Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect

- operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.
- This parameter is guaranteed but not tested.

DC CHARACTERISTICS (Over recommended operating conditions unless otherwise specified.)

Symbol	Parameter	Typ ¹	Max	Units	Conditions
I_{CC}	Quiescent Power Supply Current (CMOS Inputs) Com'l Mil	0.003 0.003	0.3 0.5	mA mA	$V_{CC} = \text{MAX}$, $f_1 = 0$, Outputs Open, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs)	0.5	2.0	mA	$V_{CC} = \text{MAX}$, $V_{IN} = 3.4V^2$, $f_1 = 0$, Outputs Open
I_{CCD}	Dynamic Power Supply Current ³	0.15	0.25	mA/ mHz	$V_{CC} = \text{MAX}$, One Input Toggling, 50% Duty Cycle, Outputs Open, $\overline{OE}_A = \overline{OE}_B = \text{GND}$, or $\overline{OE}_A = \text{GND}$, $OE_B = V_{CC}$, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
I_C	Total Power Supply Current ⁵	1.7	4.0	mA	$V_{CC} = \text{MAX}$, 50% Duty Cycle, Outputs Open, One Bit Toggling at $f_1 = 10\text{MHz}$, $\overline{OE}_A = \overline{OE}_B = \text{GND}$, or $\overline{OE}_A = \text{GND}$, $OE_B = V_{CC}$, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
		2.0	5.0	mA	$V_{CC} = \text{MAX}$, 50% Duty Cycle, Outputs Open, One Bit Toggling at $f_1 = 10\text{MHz}$, $\overline{OE}_A = \overline{OE}_B = \text{GND}$, or $\overline{OE}_A = \text{GND}$, $OE_B = V_{CC}$, $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$
		3.2	6.5 ⁴	mA	$V_{CC} = \text{MAX}$, 50% Duty Cycle, Outputs Open, Eight Bits Toggling at $f_1 = 2.5\text{MHz}$, $\overline{OE}_A = \overline{OE}_B = \text{GND}$, or $\overline{OE}_A = \text{GND}$, $OE_B = V_{CC}$, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
		5.2	14.5 ⁴	mA	$V_{CC} = \text{MAX}$, 50% Duty Cycle, Outputs Open, Eight Bits Toggling at $f_1 = 2.5\text{MHz}$, $\overline{OE}_A = \overline{OE}_B = \text{GND}$, or $\overline{OE}_A = \text{GND}$, $OE_B = V_{CC}$, $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$

Notes:

- Typical values are at $V_{CC} = 5.0V$, $+25^\circ\text{C}$ ambient.
- Per TTL driven input ($V_{IN} = 3.4V$); all other inputs at V_{CC} or GND.
- This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
- Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.
- $I_C = I_{\text{QUIESCENT}} + I_{\text{INPUTS}} + I_{\text{DYNAMIC}}$
 $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_1/2 + f_1 N_1)$
 I_{CC} = Quiescent Current with CMOS input levels
 ΔI_{CC} = Power Supply Current for a TTL High Input ($V_{IN} = 3.4V$)

 D_H = Duty Cycle for TTL Inputs High N_T = Number of TTL Inputs at D_H I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL) f_1 = Clock Frequency for Register Devices (Zero for Non-Register Devices) f_1 = Input Frequency N_1 = Number of Inputs at f_1

All currents are in milliamps and all frequencies are in megahertz.

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TRUTH TABLES

'FCT240/A/C			
Inputs			Output
$\overline{OE}_A$	$\overline{OE}_B$	D	
L	L	L	H
L	L	H	L
H	H	X	Z

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'FCT241/A/C			
Inputs			Output
$\overline{OE}_A$	OE_B	D	
L	H	L	L
L	H	H	H
H	L	X	Z

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'FCT244/A/C			
Inputs			Output
$\overline{OE}_A$	$\overline{OE}_B$	D	
L	L	L	L
L	L	H	H
H	H	X	Z

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H = HIGH Voltage Level, L = LOW Voltage Level, X = Don't Care, Z = High Impedance

AC CHARACTERISTICS

Symbol	Parameter	'FCT240				'FCT240A				'FCT240C				Units	Fig. No.
		MIL		COM'L		MIL		COM'L		MIL		COM'L			
		Min. ¹	Max.	Min. ¹	Max.	Min. ¹	Max.	Min. ¹	Max.	Min. ¹	Max.	Min. ¹	Max.		
t _{PLH} t _{PHL}	Propagation Delay Data to Output	1.5	7.5	1.5	7.0	1.5	5.1	1.5	4.8	1.5	4.7	1.5	4.3	ns	1, 2
t _{PZH} t _{PZL}	Output Enable Time	1.5	8.5	1.5	8.0	1.5	6.5	1.5	6.2	1.5	5.7	1.5	5.0	ns	1, 7, 8
t _{PHZ} t _{PLZ}	Output Disable Time	1.5	9.0	1.5	8.0	1.5	5.9	1.5	5.6	1.5	4.6	1.5	4.5	ns	

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AC CHARACTERISTICS

Symbol	Parameter	'FCT241 'FCT244				'FCT241A 'FCT244A				'FCT241C 'FCT244C				Units	Fig. No.
		MIL		COM'L		MIL		COM'L		MIL		COM'L			
		Min. ¹	Max.	Min. ¹	Max.	Min. ¹	Max.	Min. ¹	Max.	Min. ¹	Max.	Min. ¹	Max.		
t _{PLH} t _{PHL}	Propagation Delay Data to Output	1.5	7.0	1.5	6.5	1.5	5.1	1.5	4.8	1.5	4.6	1.5	4.1	ns	1, 2
t _{PZH} t _{PZL}	Output Enable Time	1.5	7.5	1.5	7.0	1.5	6.5	1.5	6.2	1.5	6.5	1.5	5.8	ns	1, 7, 8
t _{PHZ} t _{PLZ}	Output Disable Time	1.5	7.5	1.5	7.0	1.5	5.9	1.5	5.6	1.5	5.7	1.5	5.2	ns	

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ORDERING INFORMATION

PxxFCT Temp. Class	xxxx Device type	xx Package	x Processing	
				Blank
				B
				M
				P
				D
				SO
				L
				240
				241/244
				240A
				241A/244A
				240C
				241C/244C
				74
				54
				Commercial
				MIL-STD-883, Class B
				Military Temperature Range
				P
				Plastic DIP
				CERDIP
				Small Outline IC
				Leadless Chip Carrier
				240
				Inverting Octal Buffer/Line Driver
				Octal Buffer/Line Driver
				240A
				Fast Inverting Octal Buffer/Line Driver
				Fast Octal Buffer/Line Driver
				241A/244A
				Ultra Fast Inverting Octal Buffer/Line Driver
				Ultra Fast Octal Buffer/Line Driver
				240C
				Commercial
				Military

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